

## Declaration of materials compliance

Frontier Silicon Ltd. certifies that all of our integrated circuit devices with package designators as listed in the following table, are compliant with the EU Directive 2002/95/EC Restriction of Hazardous Substances in Electrical and Electronic Equipment (RoHS).

This directive bans the use of lead (Pb), mercury (Hg), cadmium (Cd) hexavalent chromium (Cr VI), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE) in products sold in the European Union after 1 July 2006.

In addition, under Stage 1 requirements of China, Ministry of Information Industry Order #39, we declare that no notifiable toxic or hazardous substances are contained in all the homogeneous materials for these parts above the limit requirements of SJ/T11363-2006.

Lead-free solder surface finish, where used, is 100% matte tin.

	Package type		
	QFN	BGA	SiP BGA
Part marking	FSxxxx FSxxxxG		
Scope	All products <sup>a</sup>		

- a. This document will be updated accordingly for any changes arising out of package/product development or in environmental legislation that are noted. Exceptions will be clearly noted in the scope section of this table.

This declaration is based on our supplier data and independent analysis of homogeneous materials.

For Frontier Silicon Ltd.



Paul McMichael  
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